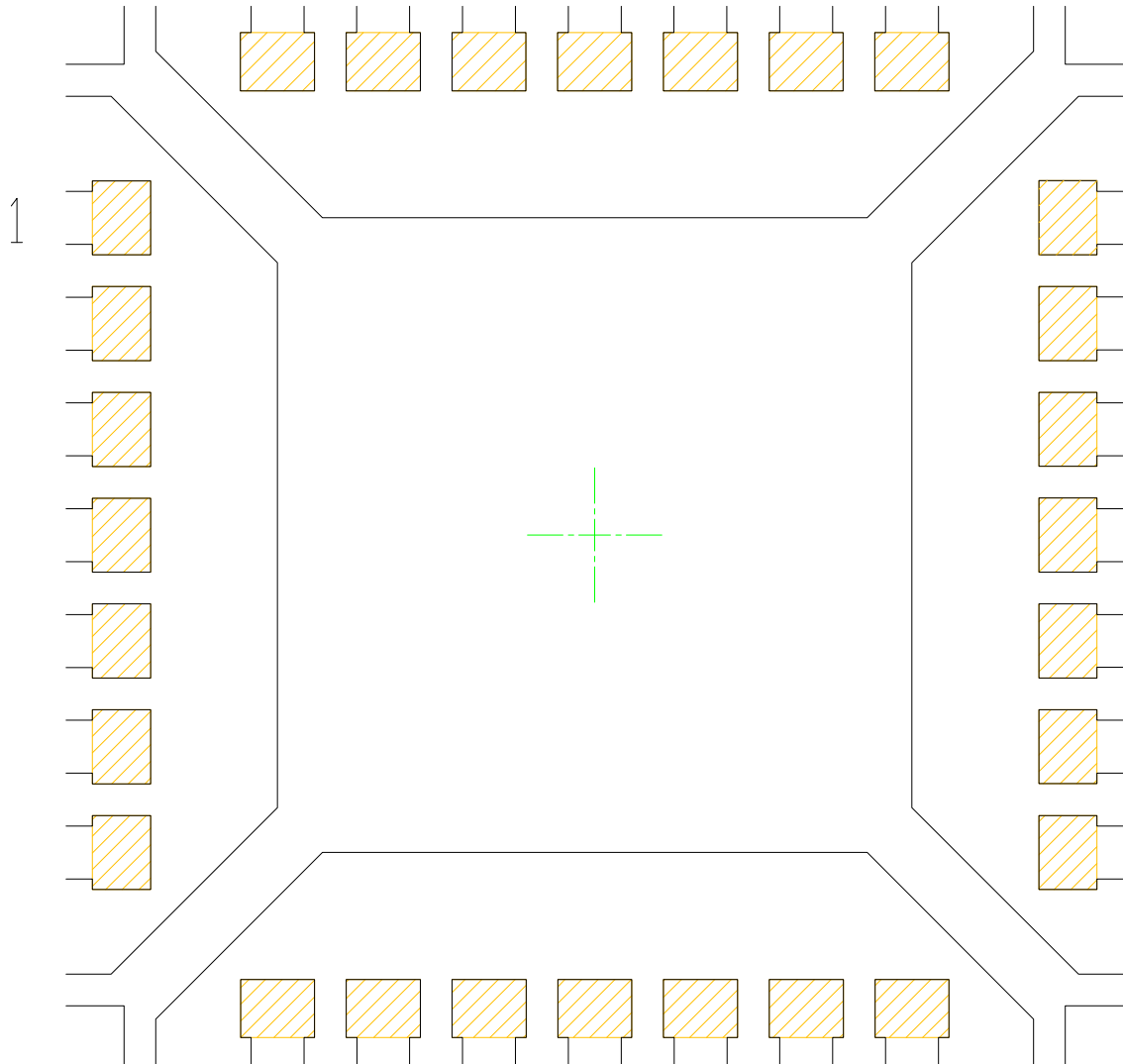



REVISIONS		
REV	DESCRIPTION	DATE
B	ADDED EXPOSED PAD SIZE AND LEADFRAME P/N	4-11-2016



 NiPdAu PLATING

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CUSTOMER: xxxxx	DOCUMENT #:	 <a href="http://www.promex-ind.com">www.promex-ind.com</a>	
PROJECT NAME: xxxxx	DIE ATTACH PAD SIZE: 3.00 x 3.00 mm		
DIE SIZE, mm: xxxxx	EXPOSED PAD SIZE: 2.80 x 2.80 mm	TITLE QFN 28L 5x5 mm 0.50 PITCH BOND SHELL	
DIE THICKNESS, um: xxxxx	DAP PLATING OPTION: BARE COPPER	LEADFRAME P/N: 235-00190	
BOND PAD PITCH, um: xxxxx	PLATING MATERIAL: NiPdAu	REV A	
BOND PAD OPENING, um: xxxxx	LEADFRAME MATERIAL: C194 FH	DO NOT SCALE	
WIRE SIZE, um: xxxxx	LEADFRAME THICKNESS: 0.203±0.0075 mm	FILE NAME 28L-QFN-5X5-50P-BD2.DWG	SHEET 1 OF 1